

	Type	Ref #	Hits	Search Text	DBs
1	BRS	L58	111	(semiconductor near1 (device package)) and tab and (thin near package)	USPAT; EPO; JPO; Derwent
2	BRS	L70	8	kitahiro adj isamu.in.	USPAT
3	BRS	L72	280	68 70	USPAT
4	BRS	L82	169	(semiconductor near chip) and (((tape film) near1 (carrier substrate)) with opening)	USPAT; EPO; JPO; Derwent
5	BRS	L87	0	82 and (stress near neutral near plane)	USPAT; EPO; JPO; Derwent
6	BRS	L92	23	stress near neutral near plane	USPAT; EPO; JPO; Derwent



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